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 Parallel-to-Serial, Serial-to-Parallel Conversions 	D OR N PACKAGE (TOP VIEW)				
 Parallel Synchronous Loading 					
 J and K Inputs to First Stage 	$\begin{array}{c} \text{CLR} \begin{bmatrix} 1 \\ 1 \end{bmatrix} & \begin{array}{c} 16 \\ \text{CLR} \end{bmatrix} \\ \text{U} \\ \text{U} \\ \text{U} \\ \text{U} \\ 15 \\ \text{U} \\ \text{Q} \\ \text{A} \end{array}$				
 Right Shift Only With Complementary 	κ[] 3 14] Q _B				
Outputs on Last Stage	A [] 4 13]] Q _C				
 Direct Overriding Clear 	в [] 5 12 [] <u>Q</u> D				
Package Options Include Plastic	C 6 11 Q _D				
Small-Outline (D) Packages and Standard					
Plastic (N) 300-mil DIPs	GND 8 9 SH/LD				

description

This 4-bit bidirectional universal shift register features parallel (A, B, C, D) inputs, parallel (Q_A , Q_B , Q_C , Q_D , \overline{Q}_D) outputs, J- \overline{K} serial (J, \overline{K}) inputs, shift/load control (SH/ \overline{LD}) input, and a direct overriding clear (\overline{CLR}). The registers have two modes of operation:

- Parallel (broadside) load
- Shift (in the direction Q_A toward Q_D)

Parallel loading is accomplished by applying the four bits of data and taking SH/LD low. The data is loaded into the associated flip-flops and appears at the outputs after the positive transition of the clock (CLK) input. During loading, serial data flow is inhibited.

Shifting is accomplished synchronously when SH/ $\overline{\text{LD}}$ is high. Serial data for this mode is entered at the J- $\overline{\text{K}}$ inputs. These inputs permit the first stage to perform as a J- $\overline{\text{K}}$, D-, or T-type flip-flop as shown in the function table.

The SN74AS195 is characterized for operation from 0°C to 70°C.

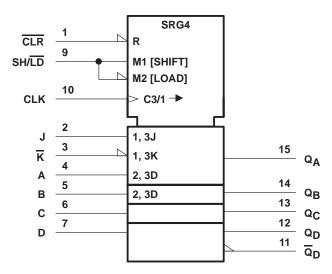
	INPUTS							C	UTPUT	S					
					SEF	RIAL		PARA	LLEL			_	_	_	_
CLR	SH/LD	CLK	J	ĸ	Α	В	С	D	QA	QB	QC	QD	QD		
L	Х	Х	Х	Х	Х	Х	Х	Х	L	L	L	L	Н		
н	L	\uparrow	Х	Х	а	b	С	d	а	b	С	d	d		
н	Н	L	Х	Х	Х	Х	Х	Х	Q _{A0}	Q_{B0}	Q _{C0}	Q_{D0}	\overline{Q}_{D0}		
н	Н	\uparrow	L	Н	Х	Х	Х	Х	Q _{A0}	Q _{A0}	Q _{Bn}	QCn	Q _{Cn}		
н	Н	\uparrow	L	L	Х	Х	Х	Х	L	Q _{An}	Q _{Bn}	QCn	Q _{Cn}		
Н	Н	\uparrow	Н	Н	Х	Х	Х	Х	н	Q _{An}	Q _{Bn}	Q _{Cn}	Q _{Cn}		
Н	Н	\uparrow	Н	L	Х	Х	Х	Х	\overline{Q}_{AN}	Q _{An}	Q _{Bn}	Q _{Cn}	Q _{Cn}		

FUNCTION TABLE



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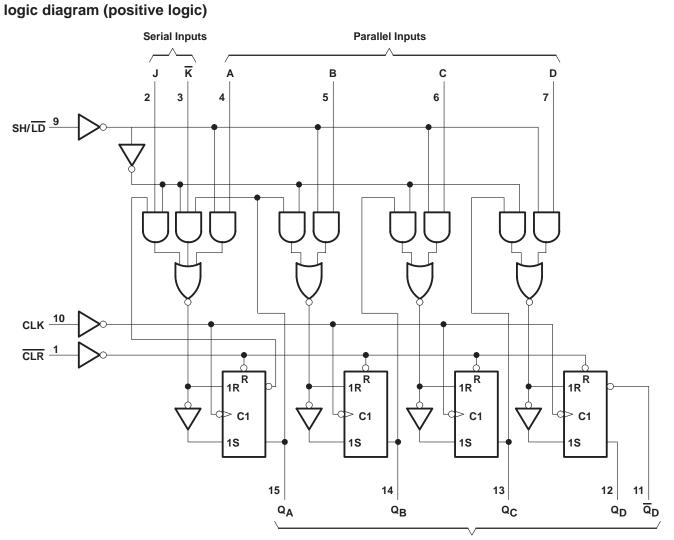
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

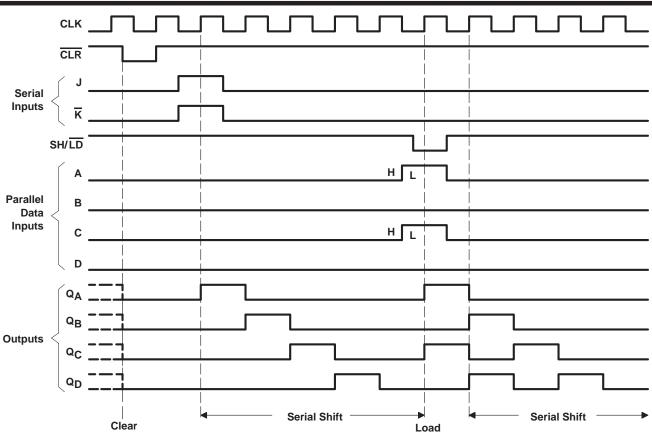


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Parallel Outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}
Input voltage, V ₁
Operating free-air temperature range, T _A
Storage temperature range

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				0.8	V
ЮН	High-level output current				-2	mA
IOL	Low-level output current				20	mA
fclock	Clock frequency		0		70	MHz
	Pulse duration	CLK high	4			
tw		CLR low	7.2			ns
	Setup time	Data before CLK↑	3.5			ns
t _{su}		SH/LD before CLK↑	8			
		CLR high before CLK [↑]	6			
		Data after CLK↑	1			
t _h	Hold time SH/LD after CLK↑		0			ns
TA	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST COND	ITIONS	MIN	TYP†	MAX	UNIT
VIK		$V_{CC} = 4.5 V,$	l _l = – 18 mA			-1.2	V
VOH		$V_{CC} = 4.5 V$ to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -	2		V
VOL		$V_{CC} = 4.5 V,$	I _{OL} = 20 mA		0.35	0.5	V
lj –	SH/LD	V _{CC} = 5.5 V,	<u>)</u>			0.2	
	All others		V _I = 7 V			0.1	mA
Iн	SH/LD	V _{CC} = 5.5 V,	V _I = 2.7 V			40	•
	All others					20	μA
	SH/LD		V _I = 0.4 V			-1	
ΙIL	All others	V _{CC} = 5.5 V,				-0.5	mA
lO‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
ICCH		$V_{CC} = 5.5 V$			32	51	mA
ICCL		$V_{CC} = 5.5 V$			36	57	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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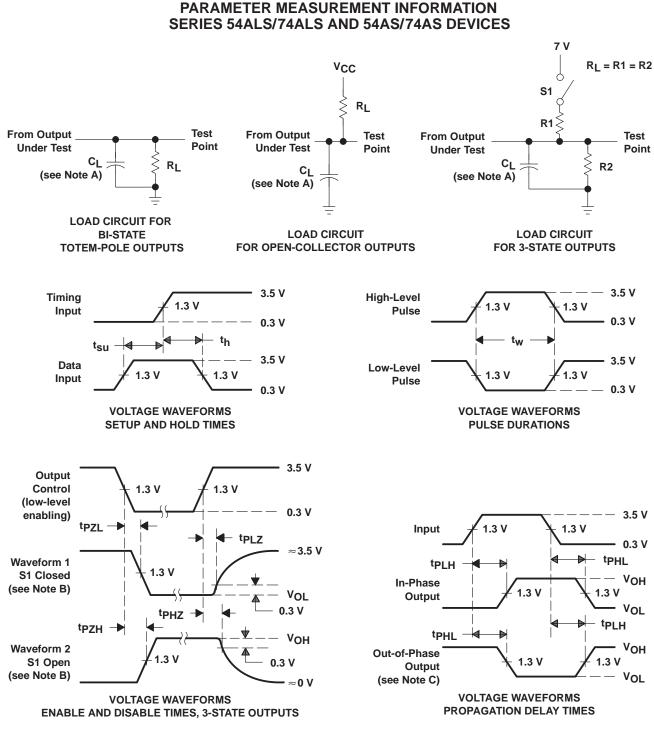
switching characteristics (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 pF R _L = 500 G T _A = MIN t	UNIT	
			MIN	MAX	
f _{max}			70		MHz
^t PLH		Amu 0	3	8.5	
^t PHL	CLK	Any Q	2.5	10.5	ns
^t PLH	CLR		4	8	ns
^t PHL	ULK	Q _A thru Q _D	5	11.5	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CI includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- All input pulses have the following characteristics: PRR \leq 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%. D.
- The outputs are measured one at a time with one transition per measurement. E.

Figure 2. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AS195N	OBSOLETE	PDIP	Ν	16	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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